



SILICON SHEET

N85-32441

SILICON SHEET SURFACE STUDIES

UNIVERSITY OF ILLINOIS AT CHICAGO

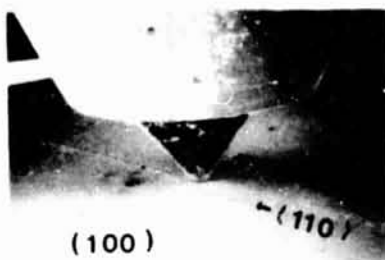
S. Danyluk

Relative Magnitudes of Residual Stresses in Web and Mobil Silicon Sheet

TECHNOLOGY	REPORT DATE October 2, 1984
<p>APPROACH Residual stresses in sheet silicon by interferometry.</p> <p>Simulation of abrasion of silicon by diamond by scratching and indentation tests.</p> <p>CONTRACTOR</p>	<p>STATUS Developed an interferometry technique for measuring residual stresses in short, thin silicon sheet.</p> <p>Measured the residual stresses in WEB and Mobil sheet.</p> <p>Correlated experimental wear rate with a wear model.</p> <p>Determined the residual stresses due to scratching.</p> <p>Showed that dislocations are associated with scratching and indentations performed at room temperature.</p>
<p>GOALS Develop non-destructive residual stress measurement technique.</p> <p>Determine wear mechanism in silicon.</p>	



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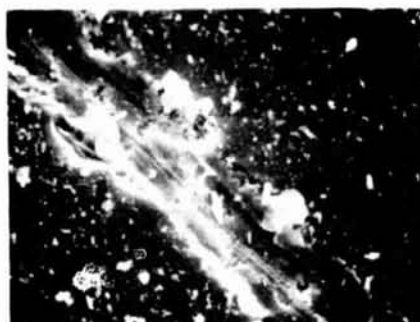
(100)

-(110)

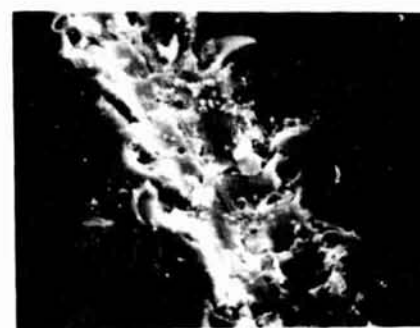
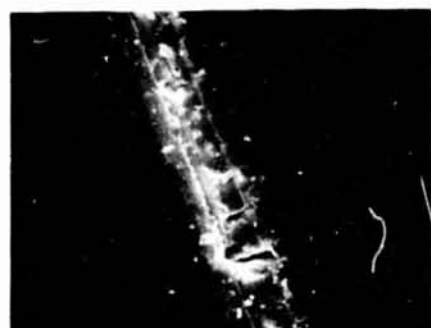
1 Scratch

10 Scratches

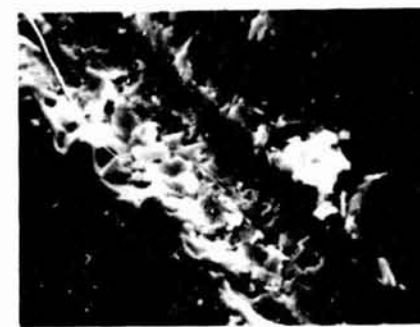
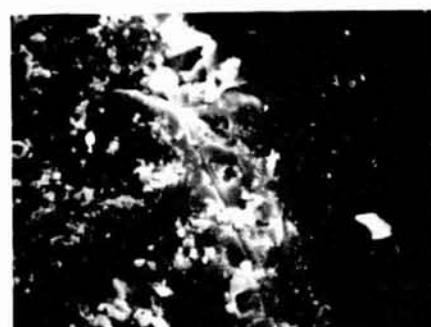
Air



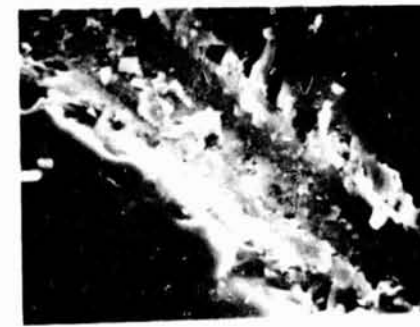
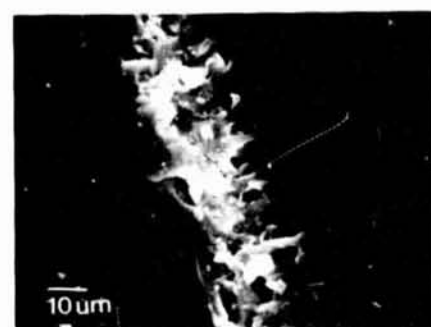
DI H₂O

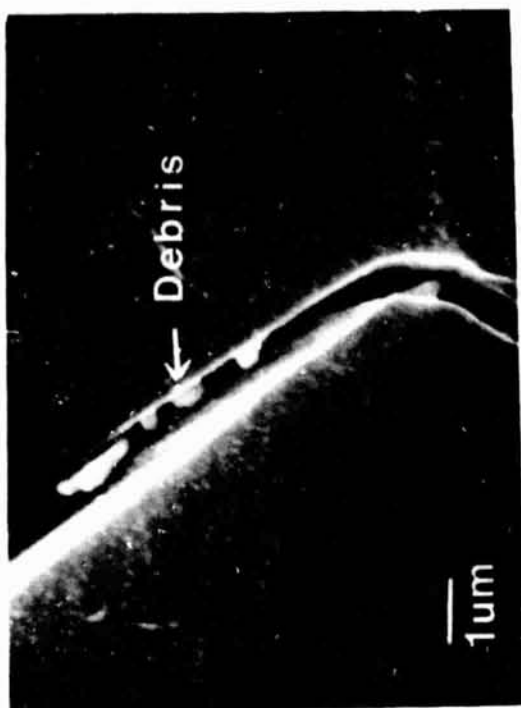
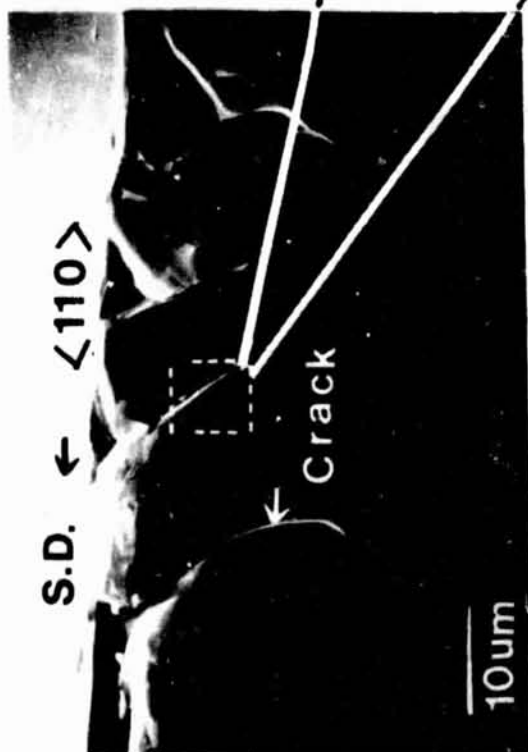


Acetone



Ethanol





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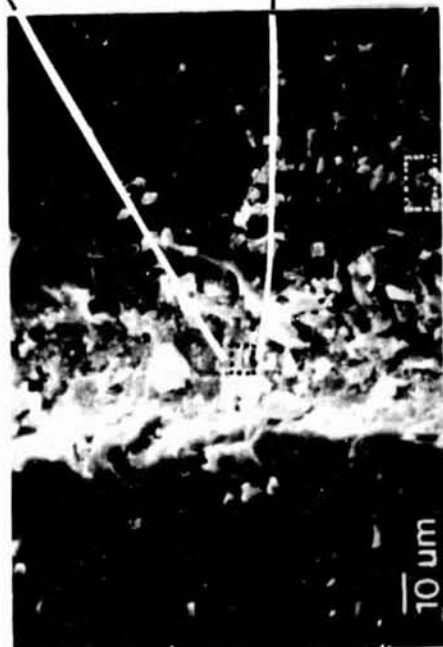
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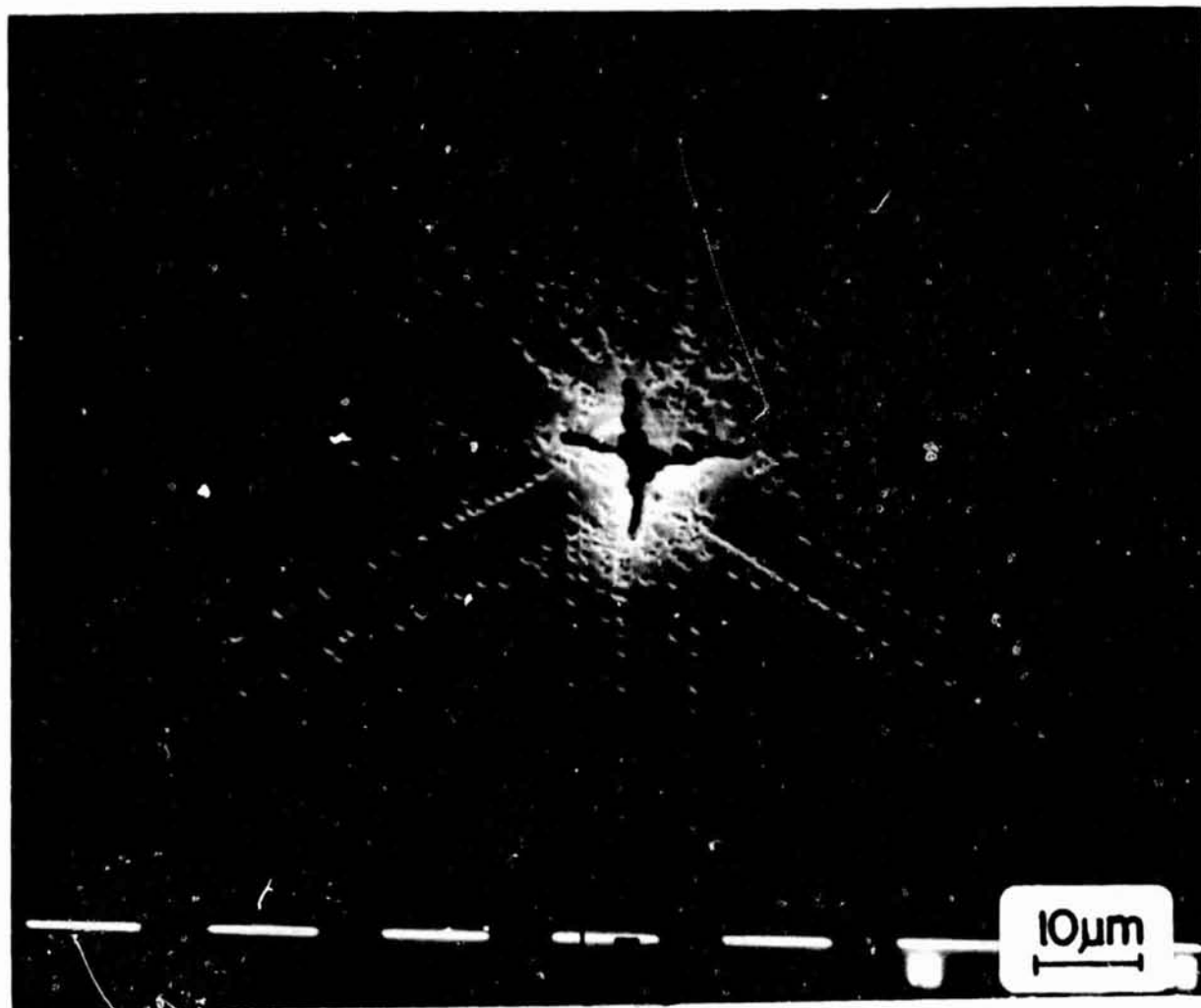
Plastic Deformation



Crack

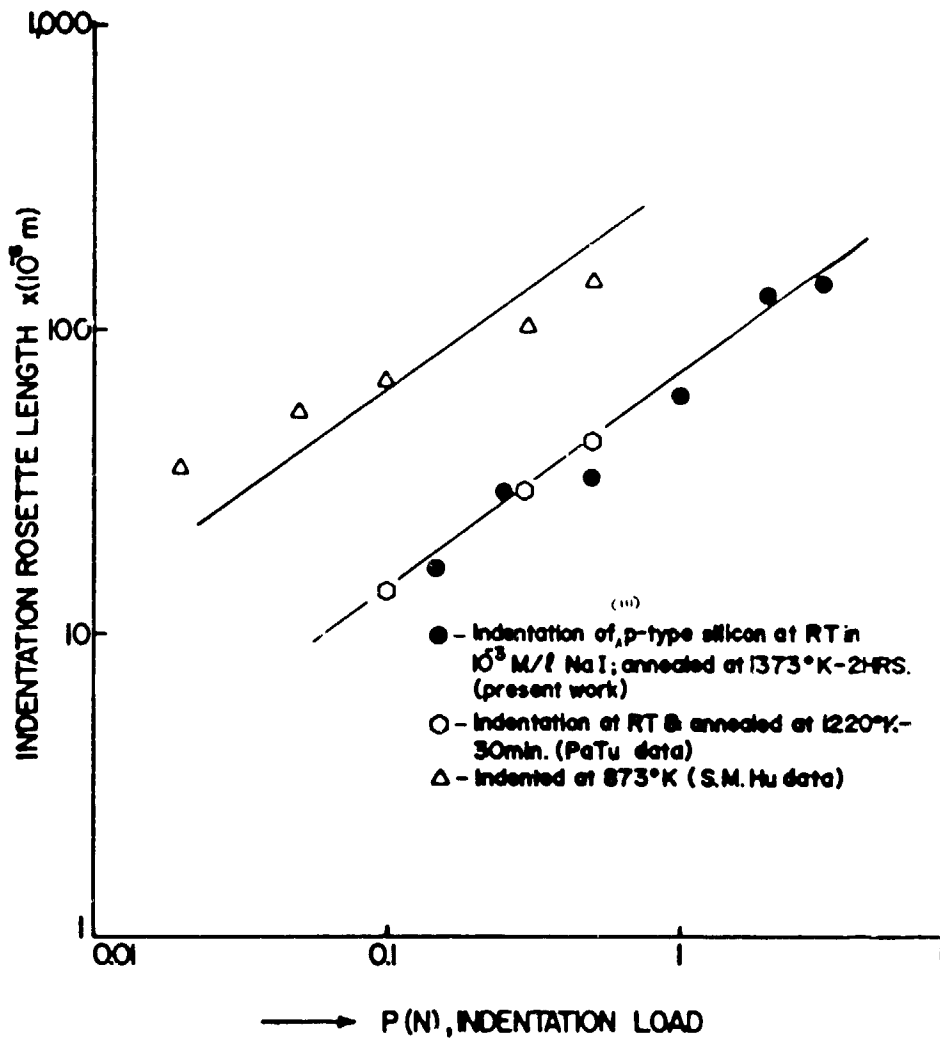
Debris

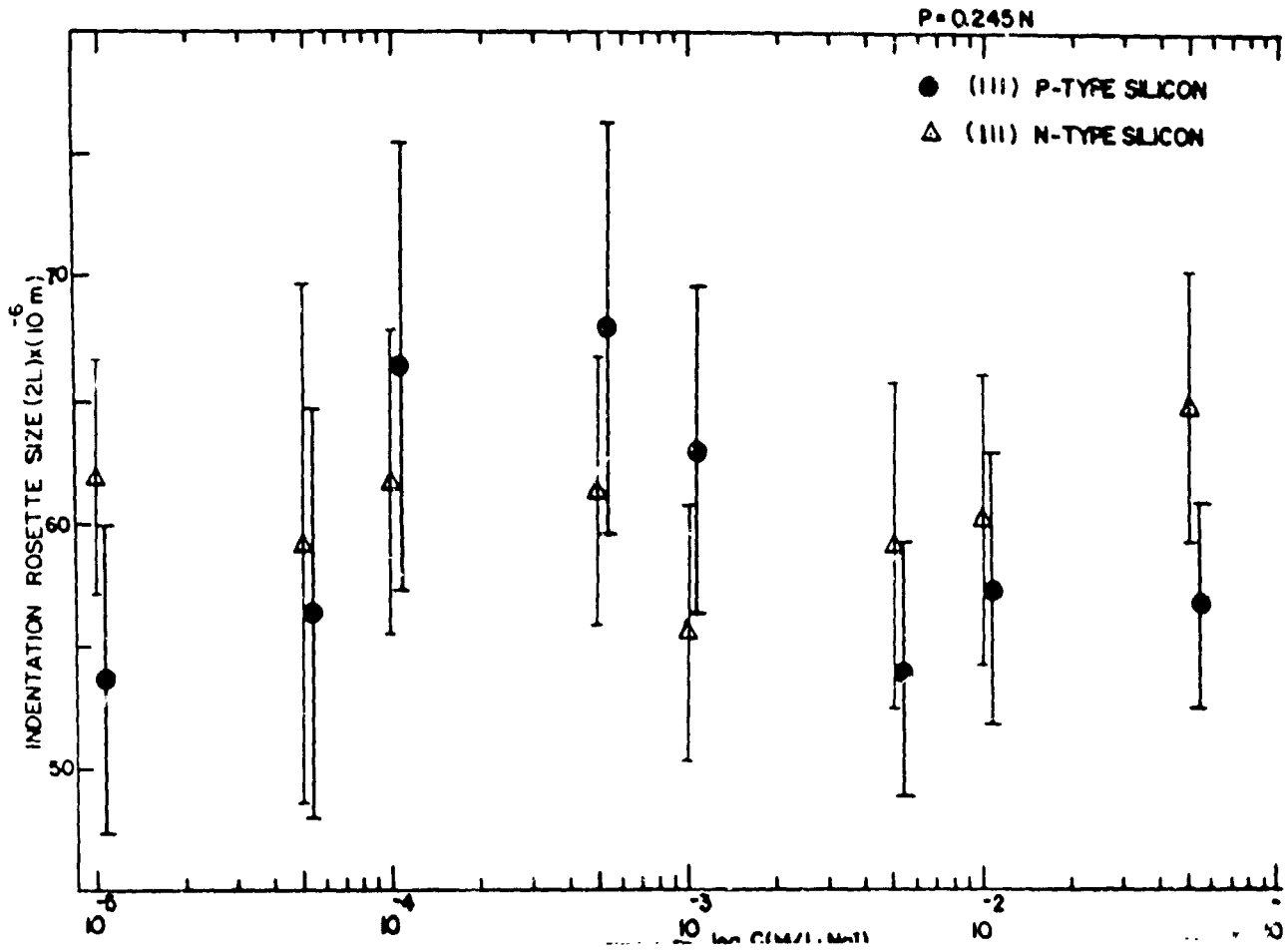




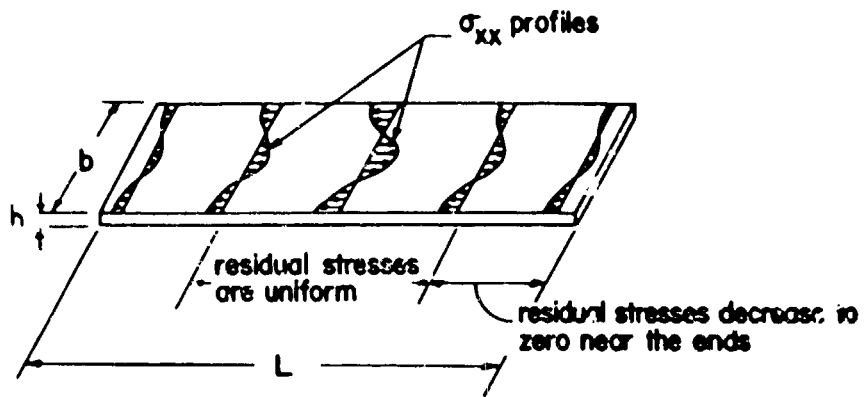
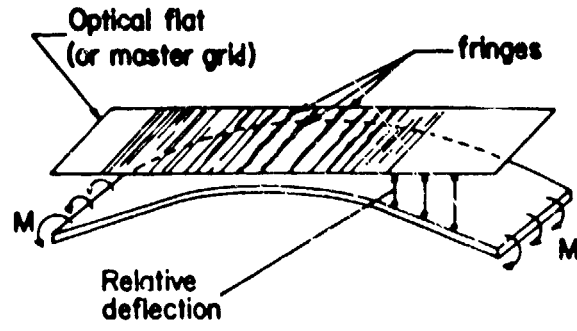
SEM MICROGRAPH OF (111) P-TYPE SILICON INDENTED
UNDER A LOAD OF 0.49N IN 10^{-3} M/L NaI;
ANNEALED AT 1373 K-2HRS AND ETCHED IN DILUTE
SIRTL SOLUTION.

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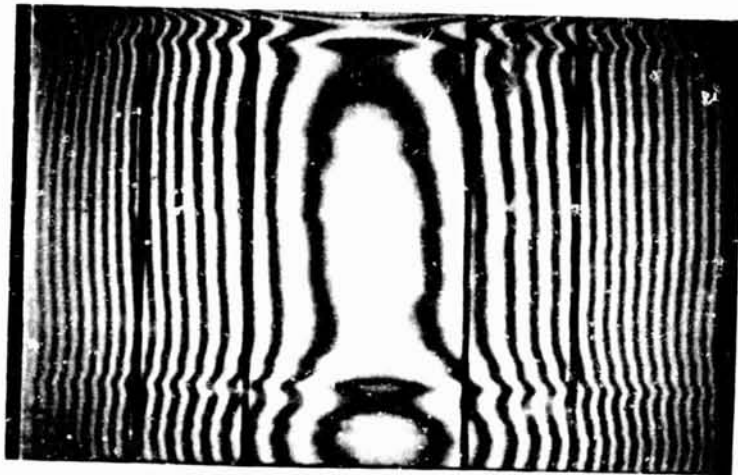
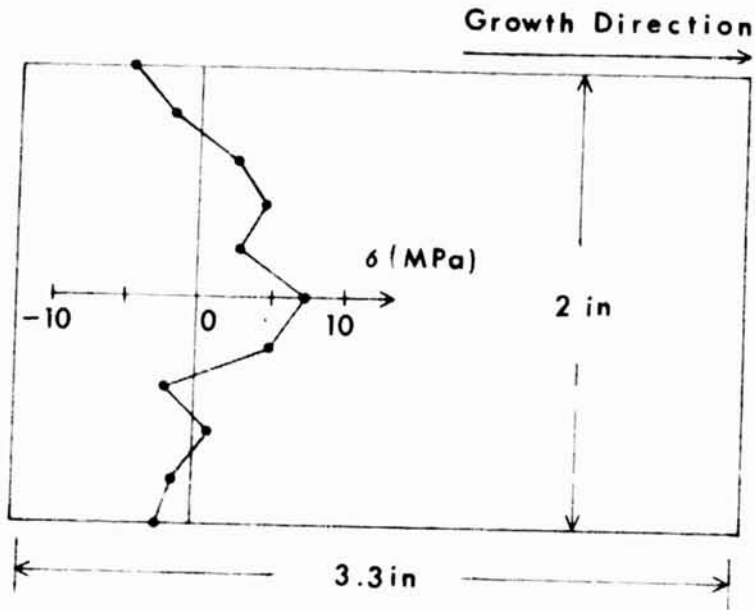


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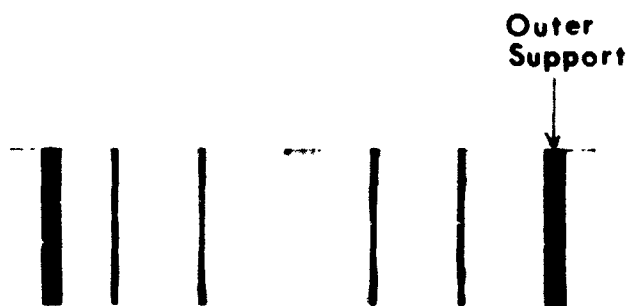
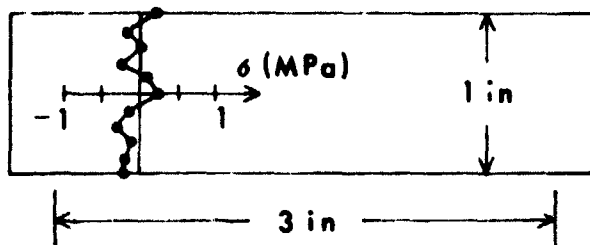


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Outer
Support



	Sample No.	Magnitude of Maximum Residual Stress (MPa)	Growth Speed (cm/min)
WEB	J515-2.3a	2.5	
	J460-2.5a	0.4	
Mobil	47R1-1	9.0	2.00
	-2	5.0	2.00
	-3	7.3	1.75
	-4	6.5	2.25

Problems and Concerns

1. Do the residual stress measurements correlate with strain gauge measurements or dislocation distributions?
2. Is the fluid chemistry changed as a result of microcrack or dislocation generation?
3. Does the abrasion mechanism change when abrasion speeds are high? What is the contact temperature.